



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20240221012.1

**Qualification of FFAB using qualified Process Technology, Die Revision, and additional Assembly site option for select devices
Change Notification / Sample Request**

Date: February 21, 2024

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) [process](#).

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240221012.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA690IDBVR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240221012.1		PCN Date:	February 21, 2024	
Title:	Qualification of FFAB using qualified Process Technology, Die Revision, and additional Assembly site option for select devices				
Customer Contact:	Change Management team		Dept:	Quality Services	
Proposed 1st Ship Date:	May 21, 2024	Sample requests accepted until:	March 22, 2024*		
*Sample requests received after March 22, 2024 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Design	<input type="checkbox"/>	Wafer Bump Material		
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/>	Wafer Bump Process		
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site		
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/>	Wafer Fab Materials		
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process		
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the addition of FFAB using the BICOMHD qualified process technology and additional Assembly site (TFME) option for the devices listed below.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SFAB	CBC10	150 mm	FFAB	BICOMHD	200 mm
The die was also changed as a result of the process change.					
Construction differences are as follows:					
	TFME	CDAT			
Bond wire composition, diameter	Au, 1.0 mil	Cu, 1.0 mil			
Lead Finish	NiPdAu	Matte Sn			
Mold Compound	SID#R-13	4222198			
Mount Compound	SID# A-03	4226215			
Device marking	NSC Logo, Pin one stripe	No Logo, Pin one dot			
<p>Upon expiry of this PCN, there will be a transition period where TI will combine lead free solutions in a single <u>standard part number</u>. For example; <u>OPA690IDBVR</u> – can ship with both Matte Sn and NiPdAu.</p> <p>Example:</p> <ul style="list-style-type: none"> Customer order for 7500 units of OPA690IDBVR with 2500 units SPQ (Standard Pack Quantity per Reel). TI can satisfy the above order in one of the following ways. <ul style="list-style-type: none"> I. 3 Reels of NiPdAu finish. II. 3 Reels of Matte Sn finish III. 2 Reels of Matte Sn and 1 reel of NiPdAu finish. IV. 2 Reels of NiPdAu and 1 reel of Matte Sn finish. <p>Qual details are provided in the Qual Data Section.</p>					
Reason for Change:					

These changes are part of our multiyear plan to transition products from our 150-millimeter and 200-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

Changes to product identification resulting from this PCN:

Fab Site

Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	TID	DEU	Freising

Die Rev:

Current

New


Die Rev [2P]	Die Rev [2P]
B	A

Assembly/Test Site

Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TFME	NFM	CHN	Economic Development Zone
TI Chengdu	CDA	CHN	Chengdu

Sample product shipping label (not actual product label)



TEXAS
INSTRUMENTS

MADE IN: Malaysia

2DC: 20:

MSL 2 /260C/1 YEAR SEAL DT

MSL 1 /235C/UNLIM 03/29/04

OPT:

ITEM: 39

LBL: 5A (L)T0:1750



G4

(1P) SN74LS07NSR

(Q) 2000 (D) 0336

(31T) LOT: 3959047MLA

(4W) TKY (1T) 7523483SI2

(P)

(2P) REV: (V) 0033317

(20L) CS0: SHE (21L) CC0:USA

(22L) AS0: MLA (23L) AC0: MYS

Product Affected:

OPA690IDBVR

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

TI Information
Selective Disclosure

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>OPA690IDBVR</u>	QBS Package Reference: <u>TLV9061IDBVR</u>	QBS Package Reference: <u>OPA328DBVT</u>	QBS Package Reference: <u>TPS3840PH30DBVRQ1</u>	QBS Package Reference: <u>LV3842XDBVR</u>	QBS Package Reference: <u>TLV9061IDBVR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	3/231/0	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	3/231/0	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: <u>OPA690IDBVR</u>	QBS Package Reference: <u>TLV9061IDBVR</u>	QBS Package Reference: <u>OPA328DBVT</u>	QBS Package Reference: <u>TPS3840PH30DBVRQ1</u>	QBS Package Reference: <u>LV3842XDBVR</u>	QBS Package Reference: <u>TLV9061IDBVR</u>
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/3000/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	3/15/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	-	3/9/0	-	1/3/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	3/9/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	3/9/0	-	1/6/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	3/90/0	-	1/30/0	3/90/0	-

- QBS: Qual By Similarity
- Qual Device OPA690IDBVR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2303-121

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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